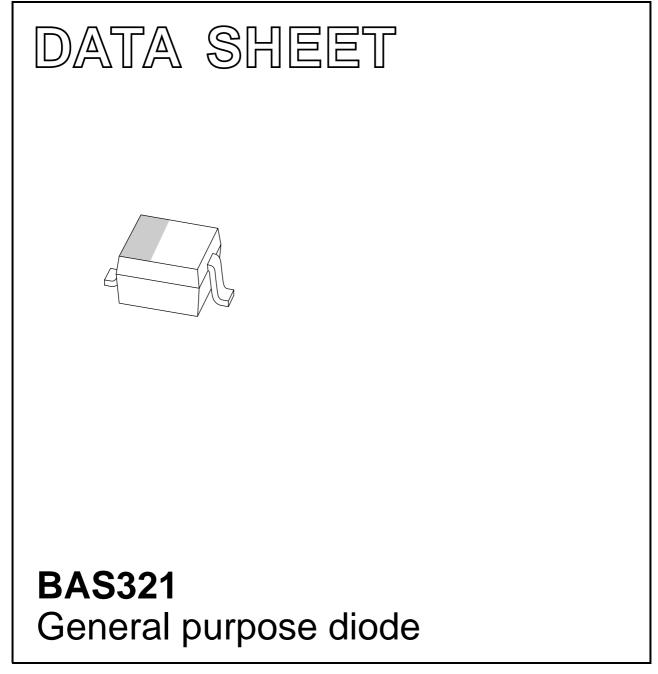
DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 1999 Feb 09 2004 Jan 26



Product data sheet

General purpose diode

FEATURES

- Small plastic SMD package
- Switching speed: max. 50 ns
- General application
- Continuous reverse voltage: max. 200 V
- Repetitive peak reverse voltage: max. 250 V
- Repetitive peak forward current: max. 625 mA.

APPLICATIONS

• General purpose switching in e.g. surface mounted circuits.

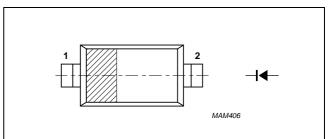
DESCRIPTION

The BAS321 is a general purpose diode fabricated in planar technology and encapsulated in a plastic SOD323 package.

ORDERING INFORMATION

PINNING

PIN	DESCRIPTION	
1	cathode	
2	anode	



Marking code: A7 The marking bar indicates the cathode.

Fig.1 Simplified outline (SOD323) and symbol.

TYPE	PACKAGE		
NUMBER NAME		DESCRIPTION	VERSION
BAS321	 plastic surface mounted package; 2 leads 		SOD323

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{RRM}	repetitive peak reverse voltage		-	250	V
V _R	continuous reverse voltage		-	200	V
I _F	continuous forward current	see Fig.2; note 1	-	250	mA
I _{FRM}	repetitive peak forward current	t_p < 0.5 ms; $\delta \le 0.25$	-	625	mA
I _{FSM}	non-repetitive peak forward current	square wave; T _j = 25 °C prior to surge; see Fig.4			
		t = 1 μs	-	9	А
		t = 100 μs	-	3	А
		t = 10 ms	-	1.7	А
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	-	300	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C

Note

1. Device mounted on an FR4 printed circuit-board.

BAS321

CHARACTERISTICS

 $T_j = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V _F	forward voltage	see Fig.3		
		I _F = 100 mA	1	V
		I _F = 200 mA	1.25	V
I _R	reverse current	see Fig.5		
		V _R = 200 V	100	nA
		V _R = 200 V; T _j = 150 °C	100	μΑ
C _d	diode capacitance	$f = 1 \text{ MHz}; V_R = 0; \text{ see Fig.6}$	2	pF
t _{rr}	reverse recovery time	when switched from I_F = 30 mA to I_R = 30 mA; R_L = 100 Ω ; measured at I_R = 3 mA; see Fig.8	50	ns

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-s)}	thermal resistance from junction to soldering point	T _s = 90°C; note 1	130	K/W
R _{th(j-a)}	thermal resistance from junction to ambient	note 2	366	K/W

Notes

1. Soldering point of cathode tab.

2. Device mounted on an FR4 printed circuit board.

BAS321

GRAPHICAL DATA

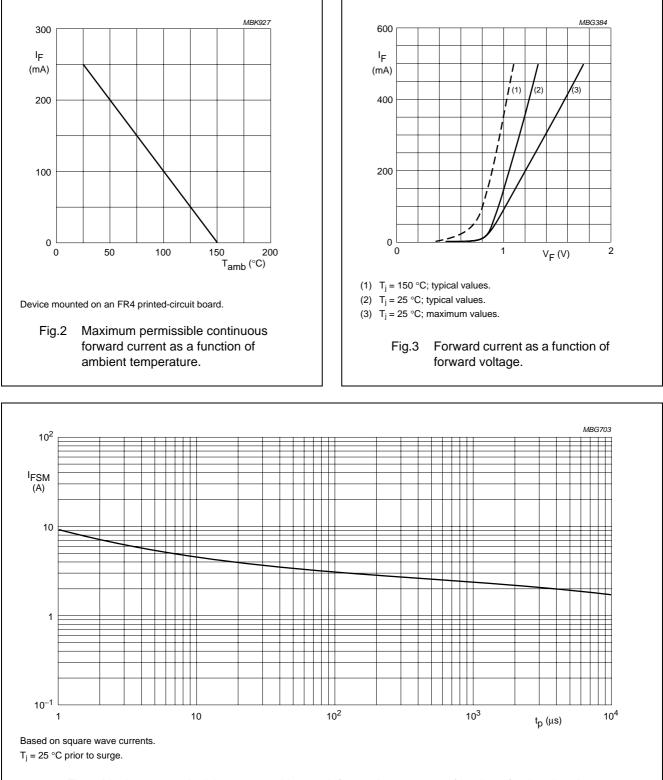
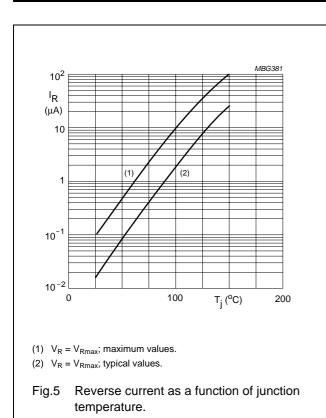
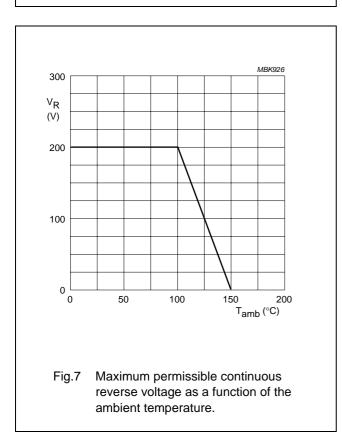
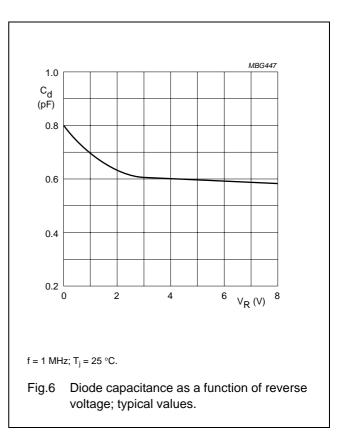
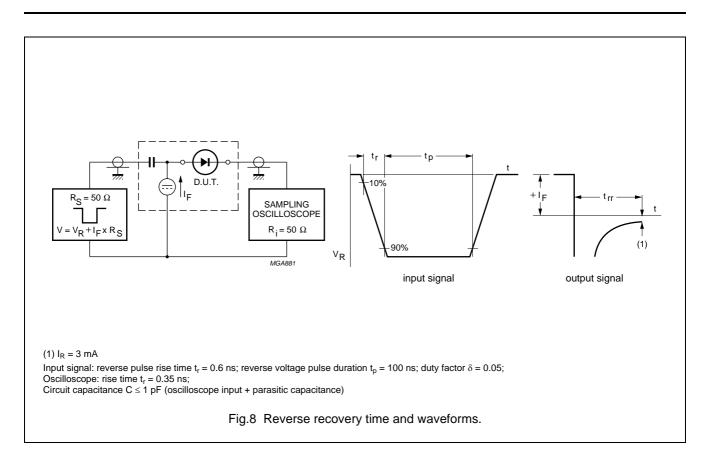


Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.



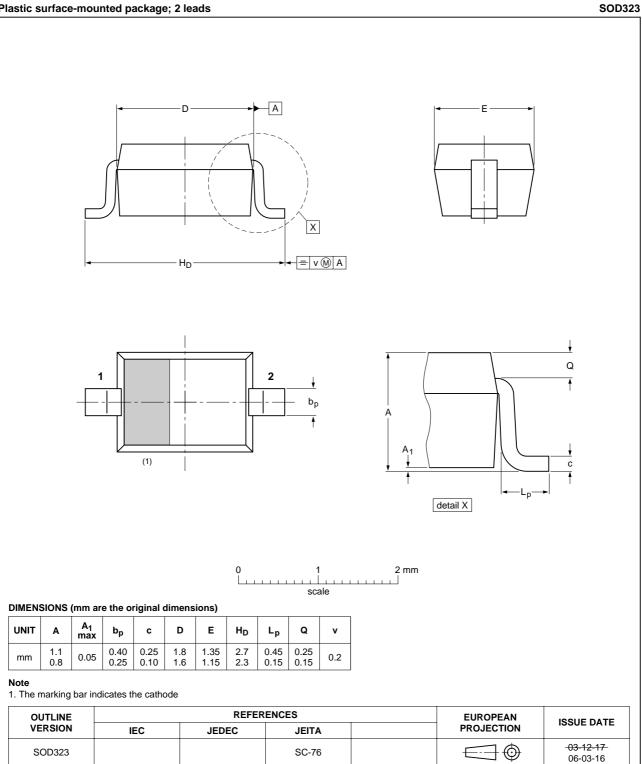






PACKAGE OUTLINE





BAS321

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

DATA SHEET STATUS

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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